



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC016N04LS G		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000988238						
<b>Package</b>		PG-TDSON-8-1		<b>Weight*</b>		119.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.396	1.17	1.17	11690	11690
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		317	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	copper	7440-50-8	37.762	31.62	31.66	316238	316650
wire	noble metal	gold	7440-57-5	0.039	0.03	0.03	325	325
encapsulation	organic material	carbon black	1333-86-4	0.086	0.07		719	
	plastics	epoxy resin	-	6.098	5.11		51066	
	inorganic material	silicondioxide	60676-86-0	36.758	30.78	35.96	307833	359618
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12157	12157
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1386	1386
solder	non noble metal	tin	7440-31-5	0.039	0.03		326	
	noble metal	silver	7440-22-4	0.049	0.04		408	
	non noble metal	lead	7439-92-1	1.862	1.56	1.63	15590	16324
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	copper	7440-50-8	11.320	9.48	9.49	94801	94924
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		187	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	copper	7440-50-8	22.292	18.67	18.70	186683	186926
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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